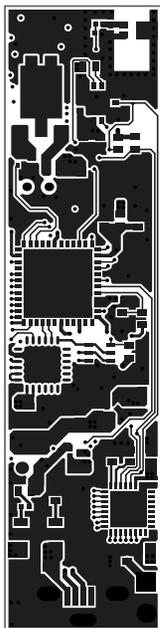


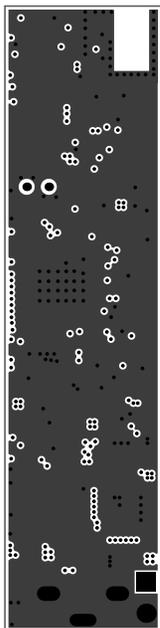
Title		
Size	Number	Revision
C		
Date:	4/26/2021	Sheet of
File:	D:\2021\Zerthor Rev E SchDoc	Drawn By:



Notes:

- 1) 0.031" Thick 6 Layer 1oz. Outer and 1oz. Inner Copper FR4 Board
- 2) Green Solder Mask Both Sides Over Tented Vias
- 3) Route to Board Outline
- 4) Add White Silk Screen Both Sides
- 5) ENIG Finish

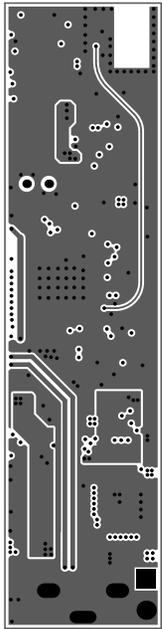
ENGINEER:		TITLE: Zephyr		Hassan Chaudhary	
PHONE:		PART NO.:		hassan789@gmail.com	
DRAWN by: 05Oct		REV: E		DATE: 21Apr20	
PHONE:		LAYER: TOP LAYER		GERBER:	
SCALE: UNITS IN INCHES					



Notes:

- 1) 0.031" Thick 6 Layer 1oz. Outer and 1oz. Inner Copper FR4 Board
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- 3) Route to Board Outline
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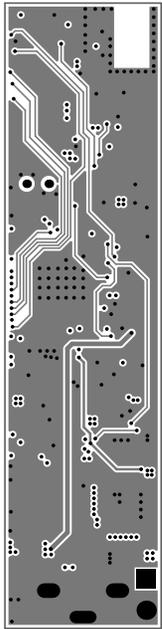
ENGINEER:		TITLE: Zephyr		Hassan Chaudhary	
PHONE:		PART NO.:		hassan789@gmail.com	
DRAWN by: 05Oct		REV: E		DATE: 21Apr20	
PHONE:		SCALE: UNITS IN INCHES		GERBER:	
		LAYER: MID LAYER 1			



Notes:

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- 4) Add White Silk Screen Both Sides
- 5) ENIG Finish

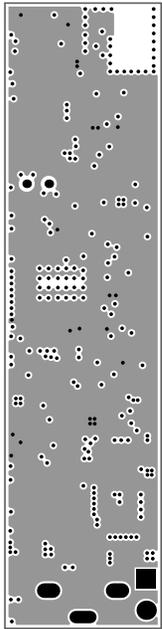
ENGINEER:	TITLE: Zephyr	Hassan Chaudhary	
PHONE:		hassan789@gmail.com	
DRAWN by: 05Oct	PART NO.:	REV: E	DATE: 21Apr20
PHONE:			
SCALE: UNITS IN INCHES	LAYER: MID LAYER 2	GERBER:	



Notes:

- 1) 0.031" Thick 6 Layer 1oz. Outer and 1oz. Inner Copper FR4 Board
- 2) Green Solder Mask Both Sides Over Tented Vias
- 3) Route to Board Outline
- 4) Add White Silk Screen Both Sides
- 5) ENIG Finish

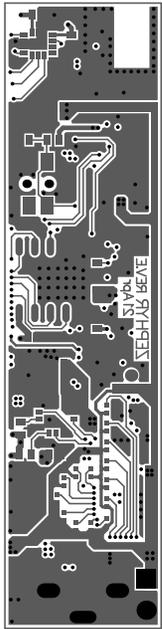
		Hassan Chaudhary hassan789@gmail.com	
ENGINEER:	TITLE: Zephyr		
PHONE:			
DRAWN by: 050ct	PART NO.:	REV: E	DATE: 21Apr20
PHONE:			
SCALE: UNITS IN INCHES	LAYER: MID LAYER 3	GERBER:	



Notes:

- 1) 0.031" Thick 6 Layer 1oz. Outer and 1oz. Inner Copper FR4 Board
- 2) Green Solder Mask Both Sides Over Tented Vias
- 3) Route to Board Outline
- 4) Add White Silk Screen Both Sides
- 5) ENIG Finish

		Hassan Chaudhary hassan789@gmail.com	
ENGINEER:	TITLE: Zephyr		
PHONE:			
DRAWN by: 050ct	PART NO.:	REV: E	DATE: 21Apr20
PHONE:			
SCALE: UNITS IN INCHES	LAYER: MID LAYER 4	GERBER:	



Notes:

- 1) 0.031" Thick 6 Layer 1oz. Outer and 1oz. Inner Copper FR4 Board
- 2) Green Solder Mask Both Sides Over Tented Vias
- 3) Route to Board Outline
- 4) Add White Silk Screen Both Sides
- 5) ENIG Finish

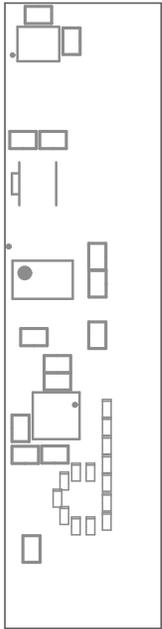
ENGINEER:		TITLE: Zephyr		Hassan Chaudhary	
PHONE:		PART NO.:		hassan789@gmail.com	
DRAWN by: 05Oct		REV: E		DATE: 21Apr20	
PHONE:		SCALE: UNITS IN INCHES		GERBER:	
		LAYER: BOTTOM LAYER			



Notes:

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- 4) Add White Silk Screen Both Sides
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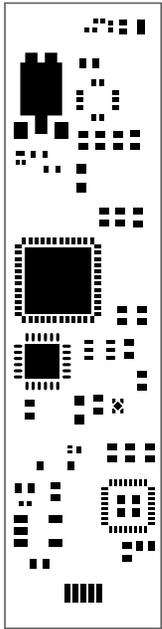
ENGINEER:		TITLE: Zephyr		Hassan Chaudhary	
PHONE:		PART NO.:		hassan789@gmail.com	
DRAWN by: 05Oct		REV: E		DATE: 21Apr20	
PHONE:		LAYER: TOP SILK SCREEN		GERBER:	
SCALE: UNITS IN INCHES					



Notes:

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- 4) Add White Silk Screen Both Sides
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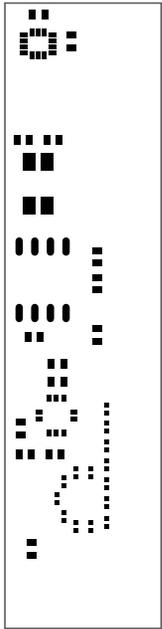
ENGINEER:	TITLE: Zephyr	Hassan Chaudhary	
PHONE:		hassan789@gmail.com	
DRAWN by: 05Oct	PART NO.:	REV: E	DATE: 21Apr20
PHONE:			
SCALE: UNITS IN INCHES	LAYER: BOT SILK SCREEN	GERBER:	



Notes:

- 1) 0.031" Thick 6 Layer 1oz. Outer and 1oz. Inner Copper FR4 Board
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- 4) Add White Silk Screen Both Sides
- 5) ENIG Finish

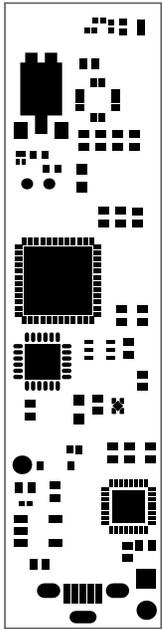
ENGINEER:		TITLE:		Hassan Chaudhary	
PHONE:		Zephyr		hassan789@gmail.com	
DRAWN by: 05Oct		PART NO.:		REV: E	
PHONE:		DATE:		21Apr20	
SCALE: UNITS IN INCHES		LAYER: TOP PASTE		GERBER:	



Notes:

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- 4) Add White Silk Screen Both Sides
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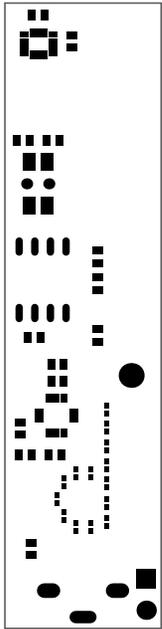
		Hassan Chaudhary hassan789@gmail.com	
ENGINEER:	TITLE: Zephyr		
PHONE:			
DRAWN by: 05Oct	PART NO.:	REV: E	DATE: 21Apr20
PHONE:			
SCALE: UNITS IN INCHES	LAYER: BOT PASTE	GERBER:	



Notes:

- 1) 0.031" Thick 6 Layer 1oz. Outer and 1oz. Inner Copper FR4 Board
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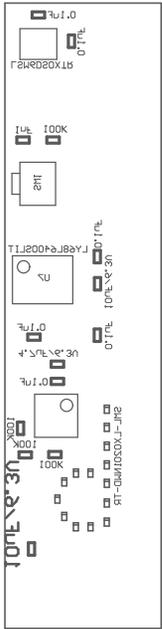
ENGINEER:		TITLE: Zephyr		Hassan Chaudhary	
PHONE:		PART NO.:		hassan789@gmail.com	
DRAWN by: 05Oct		REV: E		DATE: 21Apr20	
PHONE:		LAYER: TOP MASK		GERBER:	
SCALE: UNITS IN INCHES					



Notes:

- 1) 0.031" Thick 6 Layer 1oz. Outer and 1oz. Inner Copper FR4 Board
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- 3) Route to Board Outline
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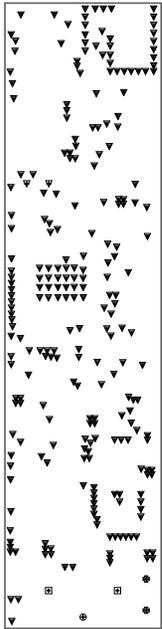
ENGINEER:		TITLE: Zephyr		Hassan Chaudhary	
PHONE:		PART NO.:		hassan789@gmail.com	
DRAWN by: 05Oct		REV: E		DATE: 21Apr20	
PHONE:		LAYER: K2AM MOTTOM		GERBER:	
SCALE: UNITS IN INCHES					



Notes:

- 1) 0.031" Thick 6 Layer 1oz. Outer and 1oz. Inner Copper FR4 Board
- 2) Green Solder Mask Both Sides Over Tented Vias
- 3) Route to Board Outline
- 4) Add White Silk Screen Both Sides
- 5) ENIG Finish

		Hassan Chaudhary hassan789@gmail.com	
ENGINEER:	<h1>Zephyr</h1>		
PHONE:			
DRAWN by: 05Oct	PART NO.:	REV: E	DATE: 21Apr20
PHONE:			
SCALE: UNITS IN INCHES	LAYER: MOTTOR YBMB224	GERBER:	



Symbol	Count	Hole Size	Hole Length	Routed Path Length	Plated	Hole Type
○	1	23.62mil (0.600mm)	62.99mil (1.600mm)	39.37mil (1.000mm)	PTH	Slot
□	2	19.69mil (0.500mm)	47.24mil (1.200mm)	27.56mil (0.700mm)	PTH	Slot
▽	2	27.56mil (0.700mm)	-	-	NPTH	Round
⊕	2	35.00mil (0.889mm)	-	-	PTH	Round
▽	247	6.00mil (0.152mm)	-	-	PTH	Round
	254 Total					

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

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		Hassan Chaudhary hassan789@gmail.com	
ENGINEER:	Zephyr		
PHONE:			
DRAWN by: 05Oct	PART NO.:	REV: E	DATE: 21Apr20
PHONE:			
SCALE: UNITS IN INCHES	LAYER: DRILL		GERBER:

